L Number	Hits	Search Text	DB	Time stamp
-	90	nikoonahad-m$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/02 13:55
-	79	nikoonahad-m$.in. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	63	nikoonahad-mehrdad$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	57	nikoonahad-mehrdad$.in. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:38
-	38	nikoonahad-mehrdad$.in. and scatter$.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:40
-	22	nikoonahad-mehrdad$.in. and (scatter$ and rotat$).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:41
-	486	scatter$.ab. and ((semiconductor or wafer) near4 surface) and scatter$.clm.	USPAT	2004/06/02 18:01
-	253	356/$.ccls. and scatter$.ab. and ((semiconductor or wafer) near4 surface) and scatter$.clm.	USPAT	2004/06/02 13:57
-	46	356/$.ccls. and scatter$.ab. and ((semiconductor or wafer) near4 surface) and scatter$.clm. and rotat$.clm.	USPAT	2004/06/04 12:05
-	46	356/$.ccls. and scatter$.ab. and ((semiconductor or wafer) near4 surface) and rotat$ and scatter$.clm. and rotat$.clm.	USPAT	2004/06/02 14:14
-	115	(356/$ or 250/$).ccls. and scatter$.ab. and x$1ray and (semiconductor or wafer)	USPAT	2004/06/02 14:16
-	31	(356/$ or 250/$).ccls. and scatter$.ab. and x$1ray and (semiconductor or wafer) and x$1ray.clm.	USPAT	2004/06/02 17:12
-	35	(356/$ or 250/$).ccls. and scatter$.ab. and (x$1ray near6 source) and (semiconductor or wafer)	USPAT	2004/06/02 17:56
-	11	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946").pn.	USPAT	2004/06/03 16:13
-	4	("6429943" "6433878" "6483580" "6451621").pn.	USPAT	2004/06/02 18:00
-	4	scatter$.ab. and ((semiconductor or wafer) near4 surface) and (neural adj network)	USPAT	2004/06/04 15:55
-	2	("6399944" "6316151").pn.	USPAT	2004/06/04 15:33
-	10	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946" "6429943" "6433878" "6483580" "6451621").pn. and rotat$	USPAT	2004/06/03 16:13

-	24	("4039370" | "4141780" | "4200396" | "4303341" | "4330213" | "4408884" | "4710642" | "4905170" | "5164790" | "5241369" | "5329357" | "5381233" | "5416594" | "5607800" | "5608526" | "5739909" | "5757671" | "5835221" | "5867276" | "5923423" | "5956148" | "5963329" | "6031615" | "6118525").PN.	USPAT	2004/06/03 16:14
-	15	("4039370" | "4141780" | "4200396" | "4303341" | "4330213" | "4408884" | "4710642" | "4905170" | "5164790" | "5241369" | "5329357" | "5381233" | "5416594" | "5607800" | "5608526" | "5739909" | "5757671" | "5835221" | "5867276" | "5923423" | "5956148" | "5963329" | "6031615" | "6118525").PN. and rotat$	USPAT	2004/06/03 16:15
-	12	("4039370" | "4141780" | "4200396" | "4303341" | "4330213" | "4408884" | "4710642" | "4905170" | "5164790" | "5241369" | "5329357" | "5381233" | "5416594" | "5607800" | "5608526" | "5739909" | "5757671" | "5835221" | "5867276" | "5923423" | "5956148" | "5963329" | "6031615" | "6118525").PN. and scatter$ and rotat$	USPAT	2004/06/03 16:15
-	4	("4710642" | "5164790" | "5241369" | "5703692").PN.	USPAT	2004/06/03 16:26
-	3	("4710642" | "5164790" | "5241369" | "5703692").PN. and scatter$ and rotat$	USPAT	2004/06/03 16:26
-	80	356/372.ior.	USPAT	2004/06/04 11:30
-	4	356/372.ior. and scatter$.ab.	USPAT	2004/06/04 11:30
-	1514	356/$.cor. and scatter$.ab.	USPAT	2004/06/04 11:31
-	1299	356/$.cor. and scatter$.ab. and scatter$.clm.	USPAT	2004/06/04 11:31
-	478	356/$.cor. and scatter$.ab. and scatter$.clm. and @pd>19980101	USPAT	2004/06/04 11:32
-	208	356/$.cor. and scatter$.ab. and scatter$.clm. and @pd>19980101 and (semiconductor or wafer)	USPAT	2004/06/04 11:38
-	13	356/340.ccls. and scatter$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:47
-	50	356/301.ccls. and scatter$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:48
-	1	("5164790").pn.	USPAT	2004/06/04 11:50
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter$.clm. and rotat$.clm.	USPAT	2004/06/04 12:06
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter$.clm. and rotat$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:17
-	9	356/335-343.ccls. and ((semiconductor or wafer) near4 surface) and scatter$.clm. and rotat$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 13:31
-	1	356/239.1-239.8.ccls. and ((semiconductor or wafer) near4 surface) and scatter$.clm. and rotat$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 14:57

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